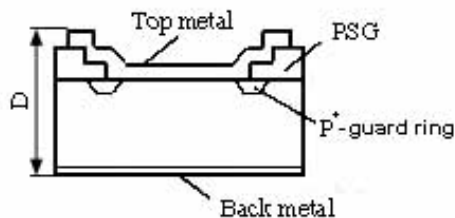
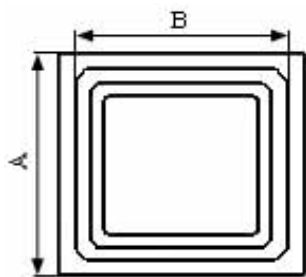


		30A/45V. Die Size-123*158mil.		
Electrical Characteristics	Symbol	Unit	Spec. limit	Die Sort
Breakdown Voltage @ $I_R=10mA$	V_{BR}	V	45	50
Average Rectified Forward Current	$I_{F(AV)}$	A	30,0	-
DC Forward Voltage @ 25°C, $I_F=15,0A$ @ 25°C, $I_F=20,0A$ @ 25°C, $I_F=30,0A$	V_F	V	0,49 0,52 0,57	0,47 0,5 0,55
Maximum Reverse Current @ 25°C, $V_R=50V$ @ 25°C, $V_R=45V$ @ 125°C, $V_R=45V$	I_R	mA	- 0,250 150,0	0,250 0,200 130,0
Peak Forward Surge Current 8,3ms single half sine-wave superimposed on rated load (JEDEC METHOD)	I_{FSM}^*	A	350	-
Peak Repetitive Reverse Surge Current @ 2,0µs, f=1kHz., $T_J<150^\circ C$.	I_{RRM}	A	5,0	
Electrostatic Discharge Voltage. JEDEC Method. ESD HBM. Contact.	V_{ESD}	kV	±8 (contact)	
Voltage Rate of Change	dV/dt	V/µS	10.000	
Operating Junction Temperature	T_J^{**}	°C	150	

* - testing for Device

** - $T_J = T_a + R_{th(j-a)} \times (P_f + P_r)$, where $R_{th(j-a)}$ – thermal resistance, P_f – forward power dissipation, P_r – revers power dissipation



DIM	ITEM	µm
Ax	Die Size	3120
Ay		4000
Bx	Top Metal Size	2980
By		3860
D	Thickness	300max.
Scribe line Width		80

Top metal:

- a) **Al** – for Wire Bonding;
- b) **Al-Ni-Ag** – for Soldering.

Backside metal: **Ti-Ni-Ag**.